



## **TSMC Shareholders Elect Board of Directors**

### **Board of Directors Unanimously Elects Dr. C.C. Wei as Chairman and CEO**

**HSINCHU, Taiwan, R.O.C., June 4, 2024** – TSMC (TWSE: 2330; NYSE: TSM) today held its 2024 Annual Shareholders' Meeting, which passed the following major resolutions:

1. Acknowledged the 2023 Business Report and Financial Statements. Consolidated revenue totaled NT\$2,161.74 billion and net income was NT\$838.50 billion, with diluted earnings per share of NT\$32.34.
2. Approved amendments to TSMC's Articles of Incorporation.
3. Approved the issuance of employee restricted stock awards (RSAs) for the year 2024.
4. Elected TSMC's 16th Board of Directors. The ten Directors are: Dr. C.C. Wei, Dr. F.C. Tseng, Dr. Ming-Hsin Kung (Representative of the National Development Fund, Executive Yuan), Sir Peter Leahy Bonfield, Mr. Michael R. Splinter, Mr. Moshe N. Gavriellov, Dr. L. Rafael Reif, Ms. Ursula M. Burns, Ms. Lynn L. Elsenhans, and Dr. Chuan Lin. Seven of those elected, Sir Peter Leahy Bonfield, Mr. Michael R. Splinter, Mr. Moshe N. Gavriellov, Dr. L. Rafael Reif, Ms. Ursula M. Burns, Ms. Lynn L. Elsenhans, and Dr. Chuan Lin are independent directors.

After the Annual Shareholders' Meeting, TSMC held the first meeting of the 16th Board of Directors, and the Board unanimously elected Dr. C.C. Wei as Chairman and Chief Executive Officer (CEO). The meeting will continue on June 5.

#### **About TSMC**

TSMC pioneered the pure-play foundry business model when it was founded in 1987 and has been the world's leading dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technologies and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry. With global operations spanning Asia, Europe, and North America, TSMC serves as a committed corporate citizen around the world.

TSMC deployed 288 distinct process technologies, and manufactured 11,895 products for 528 customers in 2023 by providing broadest range of advanced, specialty and advanced packaging



technology services. The Company is headquartered in Hsinchu, Taiwan. For more information please visit <https://www.tsmc.com>.

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